

PATENT

Docket No.: M4065.0082/P082-A

Micron No.: 98-0111.01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

11/2/00  
10/24/00  
M. T. Rugg

In re Patent Application of:  
Paul A. Farrar

Serial No.: Not Yet Assigned  
(Divisional application of Ser. No.  
09/134,363 under rule 53(b))

Group Art Unit: 2812

Filed: Concurrently Herewith

Examiner: Unassigned

For: METHOD OF FORMING A  
MICRO SOLDER BALL FOR USE  
IN C4 BONDING PROCESS

Assistant Commissioner for Patents  
Washington, D.C. 20231

FIRST PRELIMINARY AMENDMENT

Dear Sir:

Prior to examination on the merits, please amend the above-identified U.S.  
patent application as follows:

In the Specification:

Page 1, after the title, please insert --This application is a divisional of application  
Ser. No. 09/134,363, filed on August 14, 1998, now US Patent No. \_\_\_\_, which is hereby  
incorporated by reference.--

Page 2, line 11, cancel "to a a computer", substitute --to a computer--.